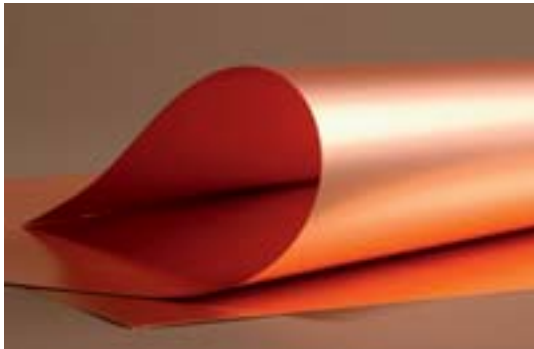


## LCP-based Circuit Materials



The R/flex® 3000 Family of Liquid Crystalline Polymer (LCP)-based Circuit Materials from Rogers Corporation includes the R/flex 3600 LCP single-clad laminate and the R/flex 3850 double-clad laminate. R/flex 3850 laminate is produced in a range of copper and film thicknesses, just as the single-clad laminate, and is available in standard panel formats. These materials offer a combination of mechanical, electrical, thermal and environmental properties for tightly controlled impedance flex interconnections, next generation wireless handsets, high-density flip-chip packages and moisture-resistance sensors. RO4000® series high frequency circuit material is a glass-reinforced hydrocarbon/ceramic thermoset laminate system designed for performance sensitive, high volume commercial applications. These laminates and prepregs are designed to offer desirable high frequency performance and circuit fabrication. The result is a low loss material, which can be fabricated using standard epoxy/glass (FR4) processes.

Rogers Corp.

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